

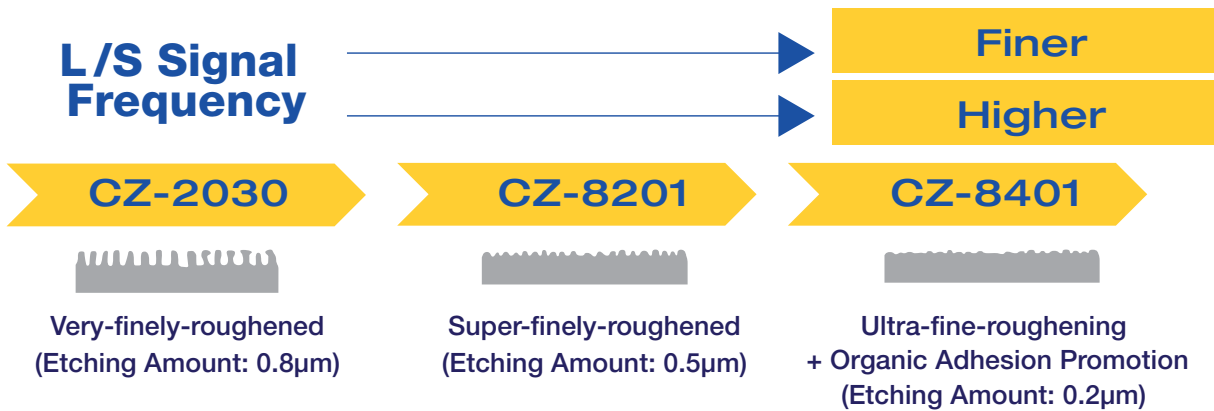


# Global Leader in Final Finish Technologies

- **TWX-42 RAIG** (Reduction-Assisted Immersion Gold) deposits 6-8 µm gold with zero nickel corrosion.
- **Talon 3** electroless palladium: the foundation for ENEPIG, EPIG and EPAG final finish layer deposits
- **TPD-23** electroless pure palladium for ENEPIG and wire bond applications
- **Direct Immersion Gold** for dense, non-porous deposits up to 0.3 µm; meets highest standards for HF and fine pattern compatibility

## MEC from Uyemura Provides Industry’s Roadmap for High Density and Ultra High Density Circuits

**Etchbond** optimizes copper bonding to resin, dry film or solder mask.



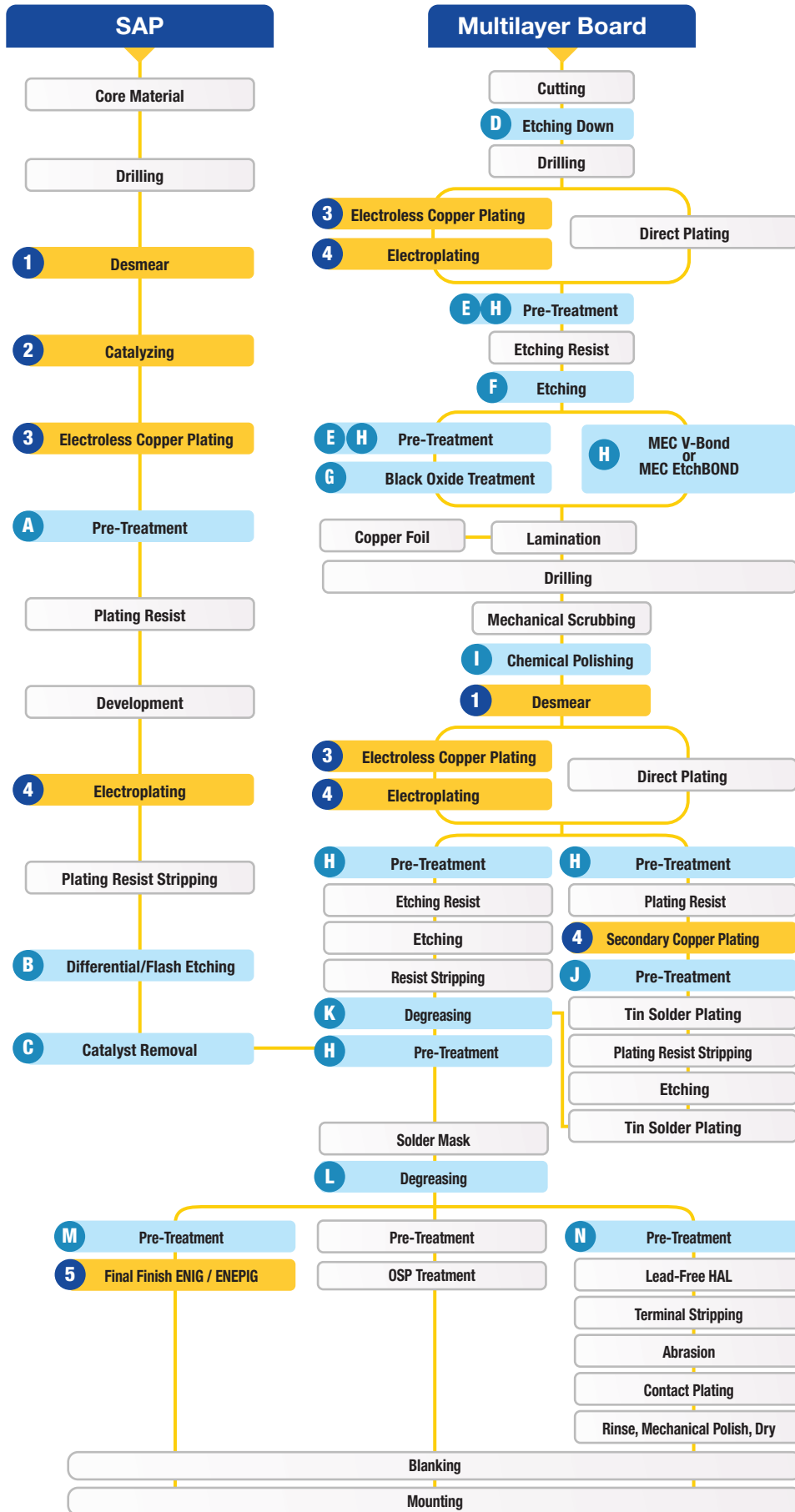
**V-BOND 7710** is an H<sub>2</sub>SO<sub>4</sub>-H<sub>2</sub>O<sub>2</sub>-type microetchant with substantial cost and maintenance advantages compared with conventional oxide alternatives. It provides exceptional inner layer adhesion to all resins, including high Tg, HF (halogen-free), and PTFE.

**Anisotropic Etching Enhancers** including EXE-6722, improve sidewall profiles and enable finer lines and higher yields.

**Flash and Differential Etchants** for SAP/mSAP provide precise controlled etching and optimize sidewall geometries.



# MEC from Uyemura IC Substrate Process Chart



## Index

### UYEMURA PRODUCTS

- 1 APPDES
- 2 ALCUP
- 3 PEA
- 4 THRU-CUP
- 5 MPC/MFD5/TALON/NPR/TWX

### MEC PRODUCTS

- A STZ-3100 or STL
- B QE-7330, CI-7200
- C PJ-9720
- D HE-7002A
- E CB-5002
- F EXE SERIES
- G V-BOND BO-7710V
- H CZ-2030, CZ-2050, or CZ-8201 (with CL-8300 or CL-2301)
- I SF-5420
- J CA-91Y, CB-801Y, CB-5620AY, or CA-5342
- K CA-5372 or CA-5342
- L CA-5342
- M CA-5330K or CA-5344
- N CZ-5480



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